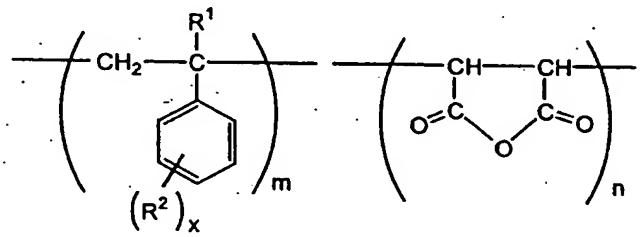
ABSTRACT

A thermosetting resin composition comprising (1) a copolymer resin comprising (a) a monomer unit and (b) a monomer unit respectively represented by the following general formulae (I) and (II):



(I) (II)

wherein R^1 represents hydrogen, a halogen, or a C_1-C_5 hydrocarbon group; R^2 represents a halogen or a C_1-C_5 hydrocarbon group; x is 0 to 3; and each of m and n is a natural number,
and (2) a cyanate resin having at least two cyanate groups per molecule.

To provide a printed wiring board material and a printed wiring board for electronic appliance, having a low dielectric constant and a low dielectric dissipation factor as well as improved heat resistance.